



**ALPHA & OMEGA**  
SEMICONDUCTOR

# AOCA32116E

## 20V Common-Drain Dual N-Channel MOSFET

### General Description

- Trench Power MOSFET technology
- Ultra low  $R_{SS(ON)}$
- Common drain configuration for design simplicity
- RoHS and Halogen-Free Compliant

### Product Summary

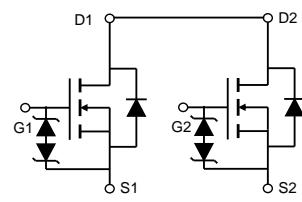
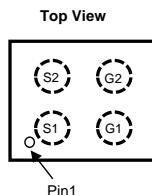
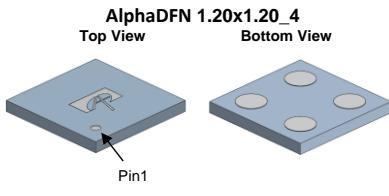
$V_{SS}$	20V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$ )	< 36mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.8V$ )	< 39mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$ )	< 44mΩ
$R_{SS(ON)}$ (at $V_{GS}=2.5V$ )	< 55mΩ

### Applications

- Battery protection switch
- Mobile device battery charging and discharging

### Typical ESD protection

HBM Class 2



### Orderable Part Number

Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOCA32116E	AlphaDFN 1.20x1.20_4	Tape & Reel	8000

### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	$V_{SS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Source Current(DC) <sup>Note1</sup>	$I_S$   $T_A=25^\circ C$	6	A
Source Current(Pulse) <sup>Note2</sup>	$I_{SM}$	25	
Power Dissipation <sup>Note1</sup>	$P_D$   $T_A=25^\circ C$	1.7	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient   $t \leq 10s$	$R_{\theta JA}$	65	°C/W
Maximum Junction-to-Ambient   Steady-State		75	°C/W

**Note 1.**  $I_S$  rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

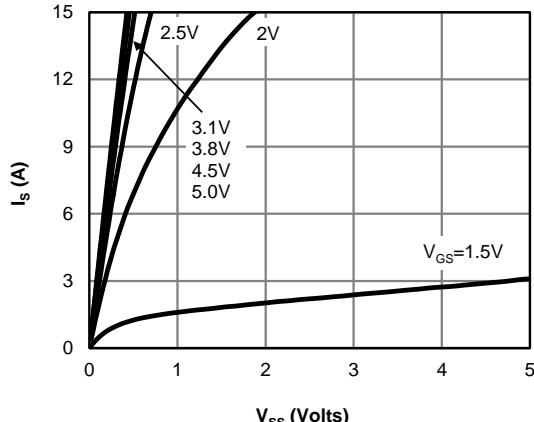
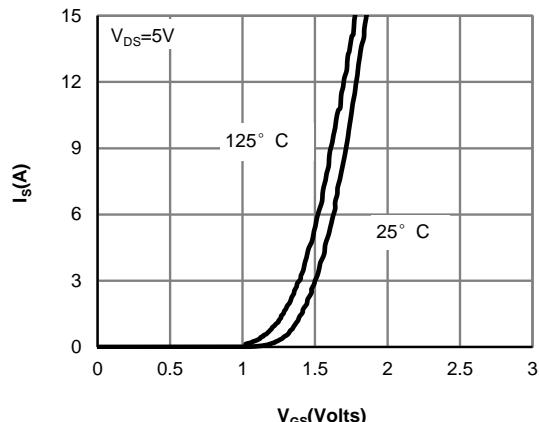
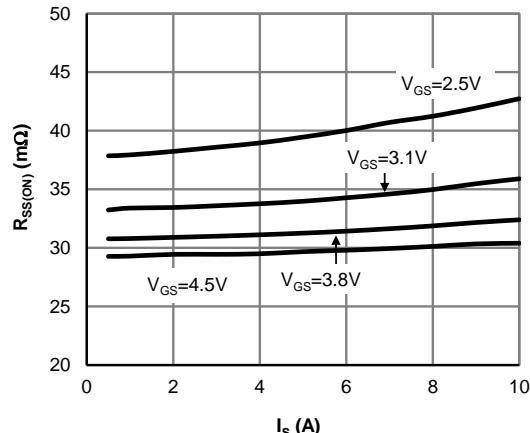
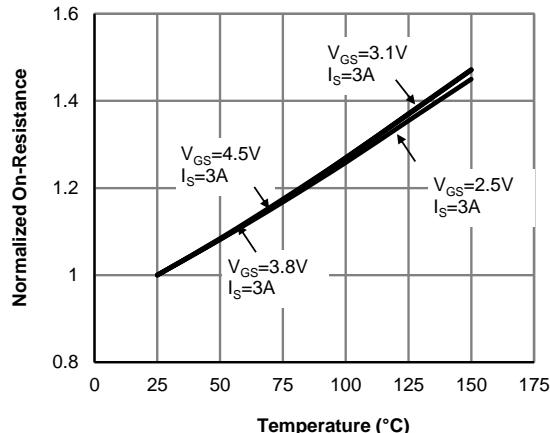
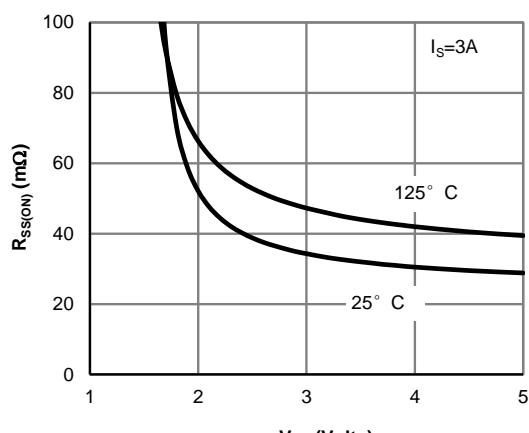
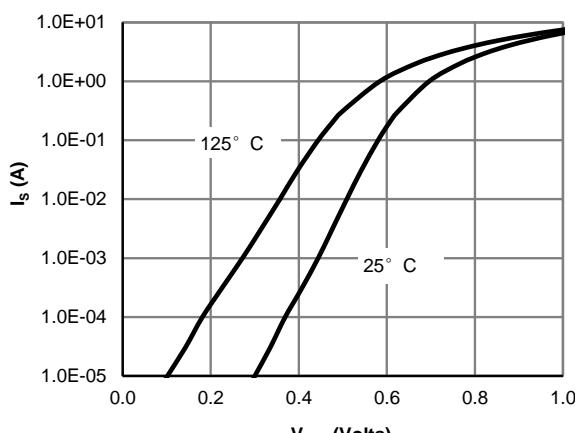
**Note 2.** PW <10  $\mu s$  pulses, duty cycle 1% max.

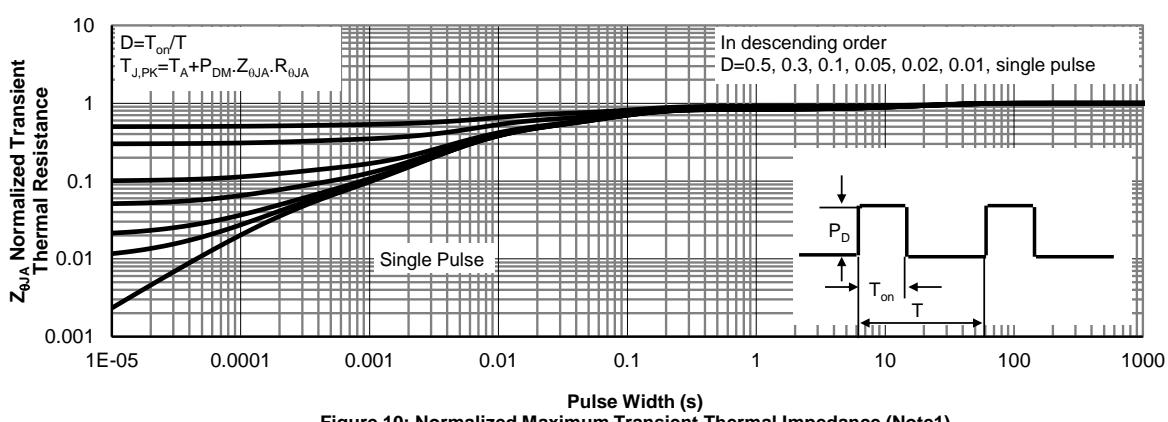
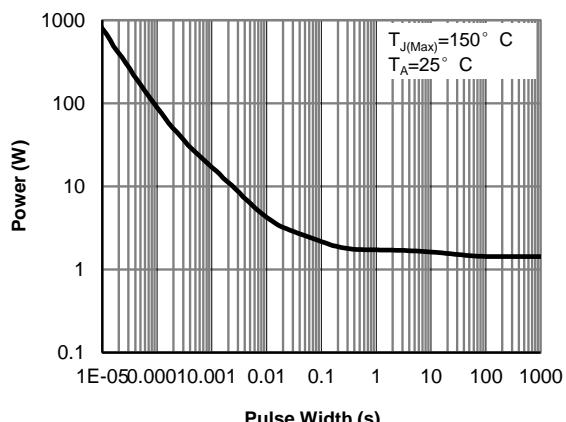
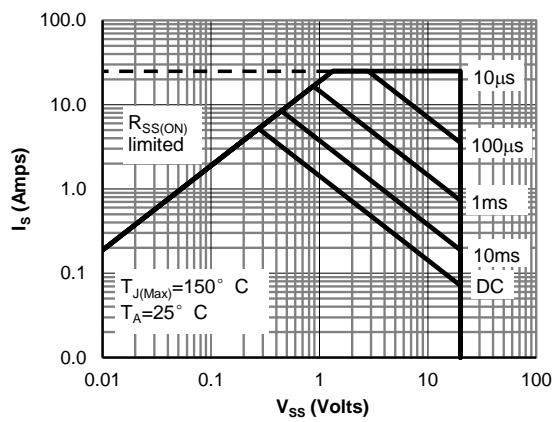
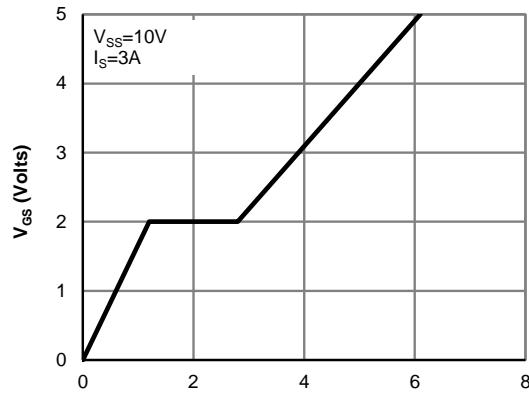
**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

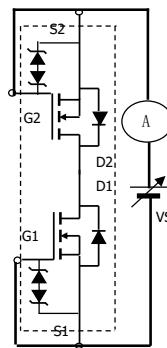
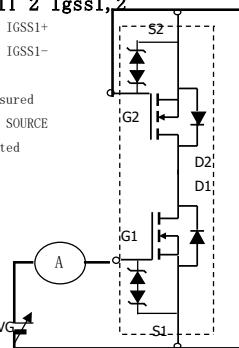
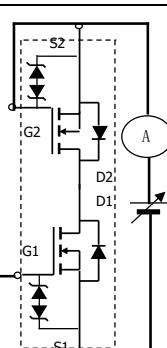
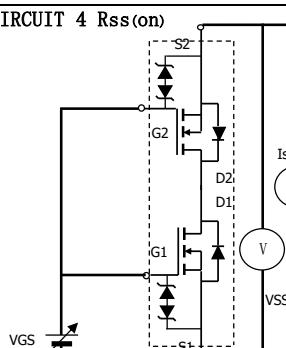
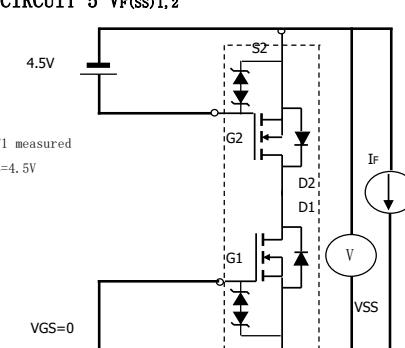
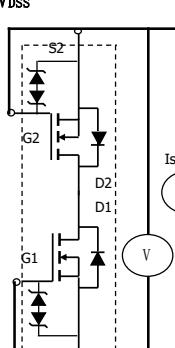
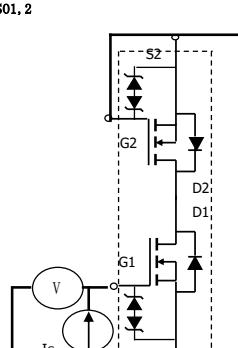
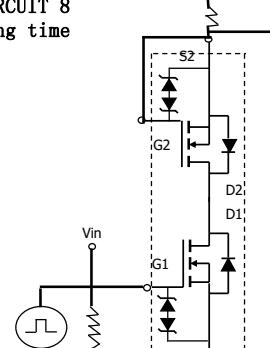
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>SSS</sub>	Source-Source Breakdown Voltage	I <sub>S</sub> =250μA, V <sub>GS</sub> =0V	Test Circuit 6	20		V
I <sub>SSS</sub>	Zero Gate Voltage Source Current	V <sub>SS</sub> =20V, V <sub>GS</sub> =0V	Test Circuit 1 T <sub>J</sub> =55°C		1 5	μA
I <sub>GSS</sub>	Gate leakage current	V <sub>SS</sub> =0V, V <sub>GS</sub> =±12V	Test Circuit 2		±10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>SS</sub> =V <sub>GS</sub> , I <sub>S</sub> =250μA	Test Circuit 3	0.5	0.85	1.3
R <sub>SS(ON)</sub>	Static Source to Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>S</sub> =3A	Test Circuit 4	20	29.5	36
		T <sub>J</sub> =125°C		28	40.5	50
		V <sub>GS</sub> =3.8V, I <sub>S</sub> =3A	Test Circuit 4	21	31	39
		V <sub>GS</sub> =3.1V, I <sub>S</sub> =3A	Test Circuit 4	23	33.6	44
V <sub>FSS</sub>	Forward Source to Source Voltage	V <sub>GS</sub> =2.5V, I <sub>S</sub> =3A	Test Circuit 4	26	38.6	55
		V <sub>SS</sub> =5V, I <sub>S</sub> =3A	Test Circuit 3		20	S
		I <sub>S</sub> =1A, V <sub>GS</sub> =0V	Test Circuit 5		0.68	1
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>SS</sub> =10V, f=1MHz		410	520	630
C <sub>oss</sub>	Output Capacitance			50	72	95
C <sub>rss</sub>	Reverse Transfer Capacitance			14	48	82
R <sub>g</sub>	Gate resistance	f=1MHz			2	KΩ
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>G1S1</sub> =4.5V, V <sub>SS</sub> =10V, I <sub>S</sub> =3A		5.5		nC
t <sub>D(on)</sub>	Turn-On Delay Time	V <sub>G1S1</sub> =4.5V, V <sub>SS</sub> =10V, R <sub>L</sub> =3.3Ω, R <sub>GEN</sub> =3Ω		0.5		μs
t <sub>r</sub>	Turn-On Rise Time			1.4		μs
t <sub>D(off)</sub>	Turn-Off Delay Time		Test Circuit 8	1.9		μs
t <sub>f</sub>	Turn-Off Fall Time			2.7		μs

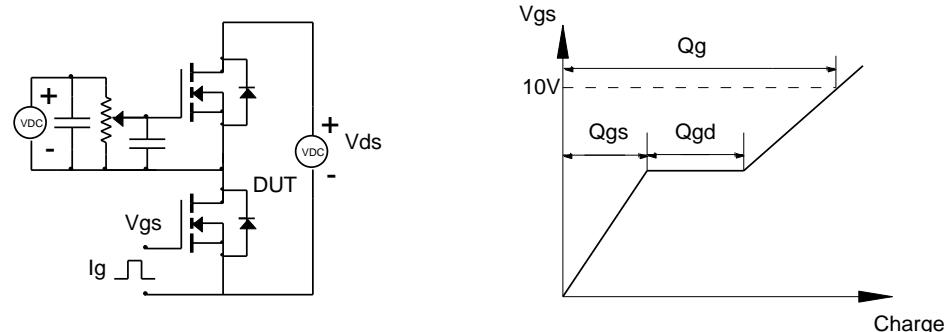
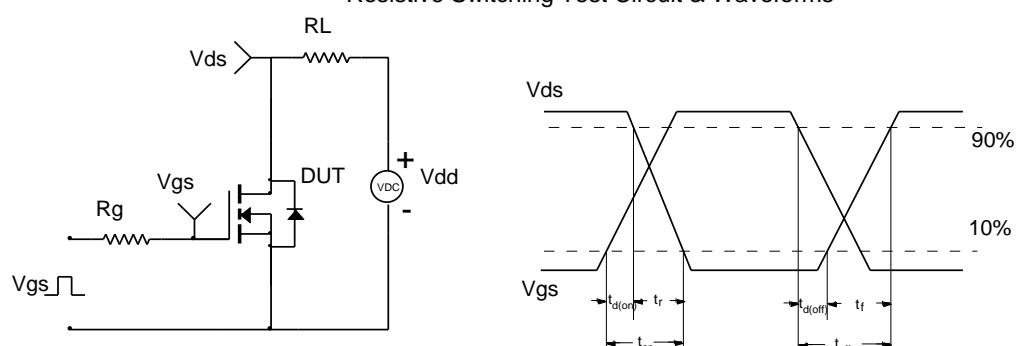
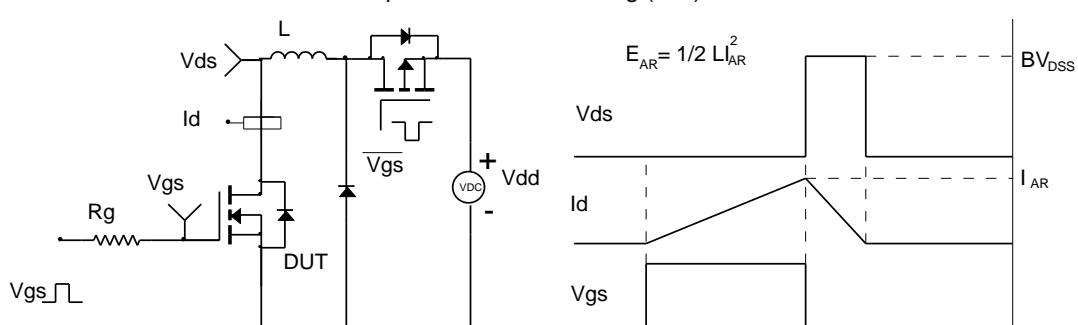
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**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 1: On-Region Characteristics**

**Figure 2: Transfer Characteristics**

**Figure 3: On-Resistance vs. Source Current and Gate Voltage**

**Figure 4: On-Resistance vs. Junction Temperature**

**Figure 5: On-Resistance vs. Gate-Source Voltage**

**Figure 6: Forward Source to Source Characteristics**

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


<b>TEST CIRCUIT 1 Isss</b> POSITIVE VSS FOR ISSS+ NEGATIVE VSS FOR ISSS- 	<b>TEST CIRCUIT 2 Igss1,2</b> POSITIVE VGS FOR IGSS1+ NEGATIVE VGS FOR IGSS1- When FET1 is measured between GATE and SOURCE of FET2 are shorted 
<b>TEST CIRCUIT 3 Vgs(off)</b> When FET1 is measured between GATE and SOURCE of FET2 are shorted 	<b>TEST CIRCUIT 4 Rss(on)</b> Vss/Is 
<b>TEST CIRCUIT 5 VF(ss)1,2</b> When FET1 measured FET2 VGS=4.5V 	<b>TEST CIRCUIT 6 BVdss</b> POSITIVE VSS FOR ISSS+ NEGATIVE VSS FOR ISSS- 
<b>TEST CIRCUIT 7 BVgs01,2</b> POSITIVE VSS FOR ISSS+ NEGATIVE VSS FOR ISSS- When FET1 is measured between GATE and SOURCE of FET2 are shorted 	<b>TEST CIRCUIT 8 Switching time</b> 

**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**
